

A Miba Group Company **Power Resistors**

Series HXP-200, SOT-227

200 W Power Resistor in the "ISOTOP" power device

Due to our Non-Inductive design, the HXP series is ideally suited for high-frequency and pulse-loading applications. Through direct mounting on a heat sink, significant cost advantage can be realized. Main applications are: variable speed drives, power supplies, control devices, telecommunications, robotics, motor controls and other switching devices.

Features

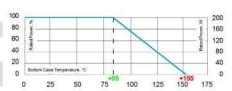
- 1x 200 W / 2x 80 W / 3x 45 W operating power
- Non-Inductive design
- ROHS compliant
- Materials in accordance with UL 94 V-0



Technical Specifications

Resistance value	0.1 O < 1 MO
Resistance tolerance	+10 % to +1 %
Temperature coefficient	> 1R: ±250 ppm/°C (at +85°C ref. to +25°C)
remperature coemicient	lower TCR on special request for limited ohmic values
Power rating	up to 200 W at 85°C bottom case temperature (see configurations)
Short time overload	1.25x rated power at 85°C bottom case temperature for 10 sec., $\Delta R = 0.4\%$ max. (for conf. 1, 2 and 3)
Maximum working voltage	500 V (up to 1,000 V on special request = "S"-version)
Partial discharge	up to 2,000 Vrms / 80pC (Tests only on special request)
Voltage proof	dielectric strength up to 4,000 V DC against ground
Insulation resistance	10 GΩ min. at 1 kV DC
Isolation voltage betweeen R1 & R2	500 V (1,000 V on special request)
Protection class	acc. to IEC 950/CSA22.2 950/M-89 and EN 60950.88:2
Comparative Tracking Index (CTI)	standard > 200 V (> 500 V on special request = "H"-version)
Heat resistance to cooling plate	Rth < 0.35 K/W
Capacitance/mass	45 pF (typical), measuring frequency 10 kHz
Serial inductivity	HXP-1 typical 40 nH, measuring frequency 10 kHz
Working temperature range	-55°C to +155°C
Mounting - max. torque for base plate (static)	1.5 Nm M4 screws
Mounting - max. torque for contacts (static)	1.3 Nm M4 screws
Weight	~26 g

Power Rating



Derating (thermal resist.) HXP-200: 2.86 W/K (0.35 K/W) (for conf. 1, 2 and 3)

* Best results can be reached by using a thermal transfer compound with a heat conductivity of at least 1 WmK. The flatness of the cooling plate must be better than 0.05 mm overall. Surface roughness should not exceed 6.4 μm .

How to make a request

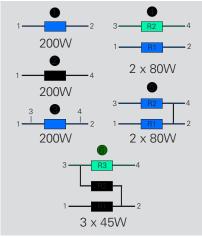
HXP-Configuration_Ohmic Value_Tolerance

For example:

HXP-1 1R 10% or HXP-4 2x50K 5%

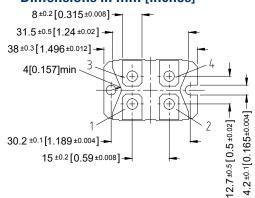
Example for higher working voltage or CTI HXP-4-S 2x40R 10% or HXPH-2 75K 5%

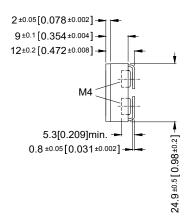
Configurations (P / package)



Version 5: ohmic value between contact 2 and $4 = 3m\Omega$

Dimensions in mm [inches]







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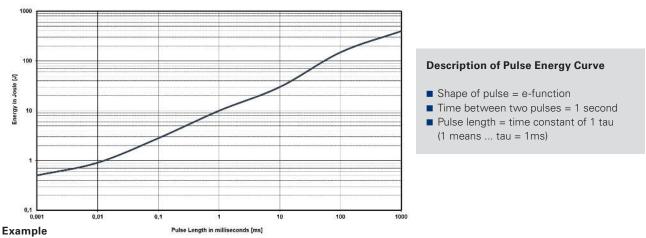
Pulse Energy Curve (typical rating for HXP-200)

Note: These energy values are reference values \rightarrow depending on ohmic value e.g. 1 Ω to 10 Ω and used resistive paste, a variation in max. energy load capability is possible

Test procedure

Every test resistor was mounted with thermal compound (0.9 W/mK) on a water cooled heatsink

- Constant inlet water temperature: +50°C
- The test time of each tested resistor: 10min.
- Break time between two pulses: 1sec.
- To determine good / defect parts the ohmic value was measured before and after tests: a change of tolerance of more than 0.1% means defect

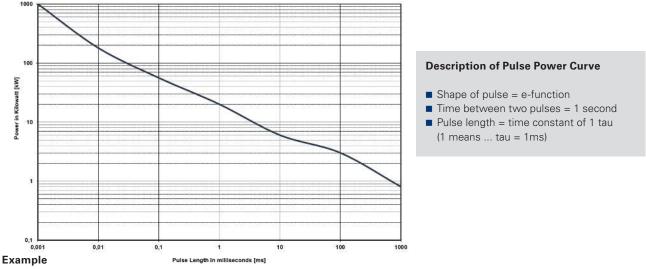


At 1 ms tau the HXP-200 with e.g. 1 Ω to 10 Ω can withstand an energy level of about 10 J, when the pulse pause time is \geq 1s

At a symmetrical frequency > 1 kHz at pulse length ≥ 10 µsec. the maximum applied pulse energy for HXP-200 is a result out of the nominal power 200 W divided by the operating frequency (at 85°C bottom case) (E = 200 W / F)

Pulse Power Curve (typical rating for HXP-200)

The power curve shows the max. possible power which can be applied for a certain duration. Referring to the same test procedure as described above.



For the time-constant of 1 ms you can apply about 20 kW max., if the time between two such peaks is \geq 1s